



## Materials Declaration Form

<b>IPC</b>	1752	<b>Version</b>	2
<b>Form Type *</b>	Distribute		
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

\* : Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2019-05-21
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier comment section	<b>Contact Title</b>	Refer to Supplier comment section
<b>Contact Phone *</b>	Refer to Supplier comment section	<b>Contact Email *</b>	Refer to Supplier comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS Material Declaration Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement	
<b>Supplier Acceptance *</b>	true
<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	77AA*MY1HAAA	A	CA2A-P1C7	2019-05-21
Amount	UoM	Unit type	ST ECOPACK Grade	
13.2	mg	Each	ECOPACK® 2	
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Gold (Ni/Au), electrolytic	Copper Alloy		



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Package Designator	Size	Nbr of instances	Shape	
LGA	2.5X3X.86	14	flat	
Comment	A08N VFLGA2.5X3X.86 14L P.5 L.475X.25; MDF is valid for LSM6DSO32TR-LSM6DSO32			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7c-I	7c-I-Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirement without any exemptions	FALSE
2 - Product(s) meets EU ELV requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
10a	Electrical and electronic components which contain lead in a glass or ceramic, in a glass or ceramic matrix compound, in a glass-ceramic material, or in a glass-ceramic matrix compound. This exemption does not cover the use of lead in: — glass in bulbs and glaze of spark plugs, — dielectric ceramic materials of components listed under 10(b), 10(c) and 10(d)

QueryList : REACH-15th January 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Homogeneous Material (mg)	Application - Homogeneous Material	ppm in Homogeneous Material

Material Composition Declaration						Mfr Item Name	77AA*MY1HAAA		13.2010		4999996.0	1000079.0				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	M-011 Other inorganic materials	5.850	mg	supplier	die	Silicon(Si)	7440-21-3		5.257	mg	898632	398258				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.010	mg	1709	758				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.038	mg	6496	2879				
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.011	mg	1880	833				
				supplier	metallisation	Tantalum(Ta)	7440-25-7		0.007	mg	1197	530				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.004	mg	684	303				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.001	mg	171	76				
				supplier	metallisation	Zirconium(Zr)	7440-67-7		0.002	mg	342	152				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.012	mg	2051	909				
				supplier	passivation	Silicon Oxide	7631-86-9		0.076	mg	12991	5758				
					JIG-R & California 65	glass	Lead-Borate Glass	65997-18-4	7c-I-Electrical and electr	0.432	mg	73846	32727			
				substrate	M-015 Other organic materials	2.403	mg	supplier	laminare	Fiber glass	65997-17-3		0.393	mg	163546	29773
								supplier	laminare	Bisphenol F type epoxy resin	9003-36-5		0.219	mg	91136	16591
supplier	laminare	Bismaleimide (B)	105391-33-1						0.133	mg	55347	10076				
supplier	laminare	Triazine (T)	25722-66-1						0.132	mg	54931	10000				
supplier	laminare	Aluminium hydroxide	21645-51-2						0.009	mg	3745	682				
supplier	laminare	Zinc hydroxide	20427-58-1						0.002	mg	832	152				
supplier	laminare	Calcium sulfate	7778-18-9						0.005	mg	2081	379				
	SVHC	laminare	BPA					80-05-7		0.001	mg	416	76			
supplier	laminare	Acrylic resin	9003-01-4						0.060	mg	24969	4545				
supplier	laminare	Barium sulfate	7727-43-7						0.025	mg	10404	1894				
supplier	laminare	epoxy resin	85954-11-6						0.022	mg	9155	1667				
supplier	laminare	Talc	14807-96-6						0.015	mg	6242	1136				
supplier	laminare	Aromatic hydrocarbon	64742-94-5						0.007	mg	2913	530				
supplier	laminare	Methoxymethylethoxy propanol	34590-94-8						0.017	mg	7074	1288				
supplier	laminare	Acetate compound	112-15-2						0.017	mg	7074	1288				
supplier	laminare	DPMA	88917-22-0		0.003	mg	1248	227								
supplier	laminare	Diphenyl-trimethylbenzoyl phosphine oxide	75980-60-8		0.003	mg	1248	227								
	M-004 Copper and its alloys	supplier	metallisation	Copper(Cu)	7440-50-8		1.167	mg	485643	88409						
	M-006 Nickel and its alloys	supplier	metallisation	Nickel(Ni)	7440-02-0		0.146	mg	60757	11061						
	M-008 Precious metals	supplier	metallisation	Gold(Au)	7440-57-5		0.027	mg	11236	2045						
Die attach	M-015 Other organic materials	0.380	mg	supplier	tape	Epoxy resin	25068-38-6		0.239	mg	628947	18106				
				supplier	tape	Polypropylene	9003-07-0		0.008	mg	21053	606				
				supplier	tape	epoxy resin	29690-82-2		0.038	mg	100000	2879				
				supplier	tape	Propenoate polymer	538311-13-6		0.076	mg	200000	5758				
				supplier	tape	Bisphenol A diglycidyl ether	1675-54-3		0.019	mg	50000	1439				
Bonding wire	M-008 Precious metals	0.102	mg	supplier	wire	Gold(Au)	7440-57-5		0.101	mg	990196	7652				
				supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	9804	76				
encapsulation	M-015 Other organic materials	4.466	mg	supplier	mold compound	Silica vitreous	60676-86-0		4.041	mg	904837	306136				
				supplier	mold compound	Epoxyde bisphenol A resin	25068-38-6		0.112	mg	25078	8485				
				supplier	mold compound	Epoxy Resin	proprietary		0.179	mg	40081	13561				
				supplier	mold compound	Phenol Resin	proprietary		0.112	mg	25078	8485				
supplier	mold compound	Carbon black	1333-86-4		0.022	mg	4926	1667								